## 507457673 08/25/2022

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
ZHIHAO CUI	08/18/2022
CHI YUEN RAYMOND KWONG	08/18/2022
CHUANJUN XIA	08/18/2022

## **RECEIVING PARTY DATA**

Name:	BEIJING SUMMER SPROUT TECHNOLOGY CO., LTD.
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City:	BEIJING
State/Country:	CHINA
Postal Code:	102308

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17895324

## **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: 80401.X.3.US.C1	
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SIGNATURE:	/Jeffrey R. Stone/
DATE SIGNED:	08/25/2022

**Total Attachments: 1** 

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PATENT REEL: 060898 FRAME: 0492

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Title: ORGANIC ELECTROLUMINESCENT MATERIALS AND DEVICES

## **ASSIGNMENT**

WHEREAS, we, CUI, Zhibao, Chi Yuen Raymond Kwong and Chuanjun Xia have invented certain new and useful improvements as described in U.S. patent application, entitled ORGANIC ELECTROLUMINESCENT MATERIALS AND DEVICES, the application having been executed on even date herewith, and/or being identified in the United States Patent and Trademark Office ("USPTO") by Application No. \_\_\_\_\_\_\_, filed \_\_\_\_\_\_\_\_, ("Invention"); and

WHEREAS, BELJING SUMMER SPROUT TECHNOLOGY CO., LTD., a Corporation of the People's Republic of China, and having an address of Room 601, 6th Floor, Building 3, No.1, Tanyuan Road, Mentougou District, Beijing, 102308, the People's Republic of China (together with its successors and assigns, the "Assignee"), seeks to memorialize its ownership of the entire right, title and interest in and to the Invention;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt and adequacy of which are hereby acknowledged, I transfer to Assignee my entire right, title, and interest in and to the Invention, including all inventions disclosed or claimed in the above-identified patent application, including any improvements thereof, any corresponding domestic applications (e.g., provisional, non-provisional, divisional, continuation, continuation-in-part, reexamination, and/or reissue patent), any corresponding foreign applications, all patents issuing thereon, or other patent application based off or claiming priority to the above-identified patent application, and all rights and benefits under any applicable treaty or convention. I authorize the USPTO (or foreign equivalent thereof) to issue any patent (or similar legal protection) to the Assignee.

I authorize the Assignee to insert in this instrument the filing date and application number of the application when ascertained. I hereby authorize the Assignee (or its designee) to apply for patent (or similar legal protection) in its own name if desired, in any and all countries.

I represent to the Assignee that I have not and shall not execute any writing or do any act whatsoever conflicting with this Assignment. I agree when requested, without additional consideration, but at the expense of the Assignee, to provide additional reasonable assistance necessary to memorialize this assignment, to execute all oaths, declarations, assignments, powers of attorney and other papers necessary to perfect and vest title to the rights assigned herein to the Assignee; and will render all assistance in filing, obtaining, maintaining, and enforcing any patent (or similar legal protection) on the Invention in any and all countries.

#### DECLARATION

I have reviewed and understand the contents of the above-identified patent application including the claims, and I believe I am an original or an original joint inventor of a claimed invention in the above-identified patent application. The above-identified patent application was made or authorized to be made by me. I am aware of and acknowledge my duty to disclose to the USPTO all information known to me to be material to patentability of the claims in the above-identified patent application. I acknowledge that any willful false statement made in this deciaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

CUI, Zhihao

Date le 12.0818

Chusnjun Xia

Date 2022-08-18

Chi Yuen Raymond Kwong

Date 2022-8-18

REEL: 060898 FRAME: 0493